

Title (en)  
SOLAR MODULE WITH SEALING ELEMENT

Title (de)  
SOLARMODUL MIT ABDICHTELEMENT

Title (fr)  
MODULE SOLAIRE COMPORTANT UN ÉLÉMENT D'ÉTANCHÉITÉ

Publication  
**EP 2795678 A1 20141029 (DE)**

Application  
**EP 12798666 A 20121129**

Priority  
• EP 11194452 A 20111220  
• EP 2012073925 W 20121129  
• EP 12798666 A 20121129

Abstract (en)  
[origin: WO2013092155A1] The present invention relates to a solar module (20), at least comprising: laminated composite assembly comprising, arranged one above another, substrate (1), back electrode layer (3), semiconductor layer (4), front electrode layer (6) and substrate (2), at least two busbars (11), which are electrically conductively connected to the back electrode layer (3) and/or the front electrode layer (6), at least one contact hole (14) arranged in at least one of the substrates (1, 2), two contact elements (9), which are electrically conductively connected to the busbars (11) and are arranged in at least one contact hole (14), at least one sealing element (17) arranged between busbar (11) and contact hole (14), and the sealing element (17) has an opening (18) above the contact hole (14), wherein a connection housing (8) closes the contact hole (14) from an outer side (I, IV) of the substrate (1, 2).

IPC 8 full level  
**H01L 31/042** (2014.01); **H01L 31/048** (2014.01)

CPC (source: EP)  
**H01L 31/02008** (2013.01); **H01L 31/02013** (2013.01); **H01L 31/046** (2014.12); **H01L 31/0465** (2014.12); **H01L 31/048** (2013.01); **Y02E 10/50** (2013.01)

Citation (search report)  
See references of WO 2013092155A1

Citation (examination)  
• WO 2011016483 A1 20110210 - SHARP KK [JP], et al & EP 2463918 A1 20120613 - SHARP KK [JP]  
• WO 2011099228 A1 20110818 - FUJI ELECTRIC SYSTEMS CO LTD [JP], et al & EP 2535943 A1 20121219 - FUJI ELECTRIC CO LTD [JP]

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**WO 2013092155 A1 20130627**; EP 2795678 A1 20141029

DOCDB simple family (application)  
**EP 2012073925 W 20121129**; EP 12798666 A 20121129